

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L8	101	(micro\$1electronic juxapos\$3) and (via hole) near4 (filling filled fill) near5 (conduct\$3 metal\$3 solder\$3) and (print\$3 wiring circuit) near3 (board substrate layer) same (pad land terminal feature) with (connect\$3 interconnect\$3) and @pd<"20020101"	USPAT; USOCR; EPO; JPO	OR	ON	2006/01/05 13:47
L10	32	(micro\$1electronic chip ic semiconductor) with juxapos\$3 and (via hole opening cavity aperture) near4 (filling filled fill) near5 (conduct\$3 metal\$3 solder\$3) and (print\$3 wiring circuit) near3 (board substrate layer) same (pad land terminal feature) with (connect\$3 interconnect\$3) and @pd<"20020101"	USPAT; USOCR; EPO; JPO	OR	ON	2006/01/05 13:49
L11	21	("4067104" "4642889" "4955523" "5067007" "5133495" "5148265" "5148266" "5203075" "5258330" "5316788" "5346861" "5398863" "5455390" "5518964" "5525545" "5557501" "5590460" "5615824" "5650914" "5679977" "5688716").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/01/05 14:25
L12	45	("0406704" "3373481" "3795037" "3811186" "3825353" "3952404" "4142288" "4326663" "4447857" "4520562" "4629957" "4661192" "4667219" "4721995" "4751199" "4785137" "4793814" "4812191" "4893172" "4926241" "4949158" "4954877" "4955523" "5047830" "5049085" "5055907" "5057460" "5067007" "5086337" "5131852" "5152695" "5166988" "5173055" "5192716" "5197892" "5210939" "5230931" "5254811" "5286680" "5346861" "5455390" "5518964" "5528083").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/01/05 14:26
L13	151	("4893172").URPN.	USPAT	OR	ON	2006/01/05 14:29
L14	4	("4893172" "5810609" "5812378" "5973394").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/01/05 14:38
S42	58	(micro\$1electronic juxapos\$3) and (via hole) near4 fill\$3 near5 (conduct\$3 metal\$3 solder\$3) same (pad land terminal feature) with (connect\$3 interconnect\$3) and @pd<"20020101"	USPAT; EPO; JPO	OR	ON	2006/01/05 12:33

S45	11	(via hole) with (plat\$3 deposit\$3 fill\$3) with (conduct\$3 metal\$3 solder\$3) with (no without "not" eliminat\$3) with seed\$3 and (pad land terminal feature) with (connect\$3 interconnect\$3) and @pd<"20020101"	USPAT; EPO; JPO	OR	ON	2005/12/20 15:42
S47	408	(via hole) with (deposit\$3 fill\$3) with (conduct\$3 metal\$3 solder\$3) and (pad land terminal feature) with (connect\$3 interconnect\$3) and (micro\$1electronic juxapos\$3) and @pd<"20020101"	USPAT; EPO; JPO	OR	ON	2005/12/20 16:46
S48	56	"29"/\$.ccls. and S47	USPAT; EPO; JPO	OR	ON	2005/12/20 16:52
S49	45	"174"/\$.ccls. and S47	USPAT; EPO; JPO	OR	ON	2005/12/20 16:55
S50	43	"361"/\$.ccls. and S47 not S48	USPAT; EPO; JPO	OR	ON	2005/12/20 16:59
S51	204	"257"/\$.ccls. and S47 not S48 not S50	USPAT; EPO; JPO	OR	ON	2005/12/20 16:59
S52	45	("0406704" "3373481" "3795037" "3811186" "3825353" "3952404" "4142288" "4326663" "4447857" "4520562" "4629957" "4661192" "4667219" "4721995" "4751199" "4785137" "4793814" "4812191" "4893172" "4926241" "4949158" "4954877" "4955523" "5047830" "5049085" "5055907" "5057460" "5067007" "5086337" "5131852" "5152695" "5166988" "5173055" "5192716" "5197892" "5210939" "5230931" "5254811" "5286680" "5346861" "5455390" "5518964" "5528083").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/20 18:05